## TTC 2022, TESLA Technology Collaboration



Contribution ID: 42 Type: not specified

## HiPIMS Nb on seamless Cu substrates: different ways to fabricate seamless substrates, and their results in a vertical cryostat, L. Vega Cid (CERN)

Wednesday, 26 January 2022 16:00 (20 minutes)

Session Classification: WG2